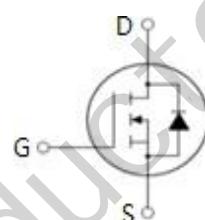


## FEATURES

- Proprietary New Planar Technology
- RDS(ON),typ.=50m  $\Omega$ @VGS=10V
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode

## APPLICATIONS

- DC-DC Converters
- DC-AC Inverters for UPS
- SMPS and Motor controls



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Value	Unit
		TO-220	
Drain-Source Voltage	$V_{DSS}$	200	V
Continuous Drain Current	$I_D$	40	A
Pulsed Drain Current (note1)	$I_{DM}$	160	A
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Single Pulse Avalanche Energy (note1)	$E_{AS}$	191	mJ
Avalanche Current (note1)	$I_{AS}$	31	A
Repetitive Avalanche Energy (note1)	$E_{AR}$	124	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	104	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150	$^\circ\text{C}$

### Thermal Resistance

Parameter	Symbol	Value	Unit
		TO-220	
Thermal Resistance, Junction-to-Case	$R_{thJC}$	1.2	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	60	

**Specifications  $T_J = 25^\circ\text{C}$ , unless otherwise noted**

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	200	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 200\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1	$\mu\text{A}$
		$V_{\text{DS}} = 200\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$	--	--	100	
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	--	4.0	V
Drain-Source On-Resistance (Note4)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	--	0.05	0.06	$\Omega$
Forward Transconductance (Note4)	$g_{\text{fs}}$	$V_{\text{DS}} = 25\text{V}, I_D = 20\text{A}$	--	16	--	S
<b>Dynamic</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$	--	2800	--	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		--	355	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	101	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 160\text{V}, I_D = 40\text{A},$	--	154	--	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		--	13	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	58	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 160\text{V}, I_D = 40\text{A}, V_{\text{GS}} = 15\text{V}, R_G = 25\Omega$	--	46	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	54	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	360	--	
Turn-off Fall Time	$t_f$		--	96	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source Current	$I_{\text{SD}}$	Integral PN-diode in MOSFET	--	--	40	$\text{A}$
Pulsed Source Current	$I_{\text{SM}}$		--	--	160	
Body Forward Voltage	$V_{\text{SD}}$	$I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.4	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_{\text{GS}} = 0\text{V}, I_F = 10\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	--	152	--	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		--	1	--	$\mu\text{C}$

**Notes:**

- Repetitive Rating: Pulse width limited by maximum junction temperature
- $L = 1\text{mH}, V_{\text{DD}} = 30\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$

Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )

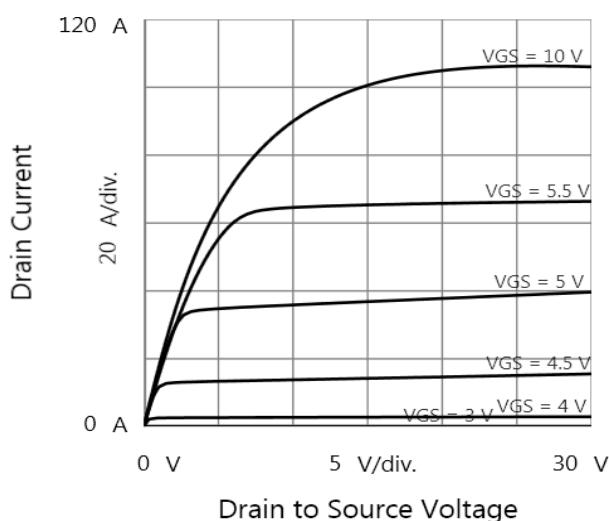


Figure 2. Transfer Characteristics

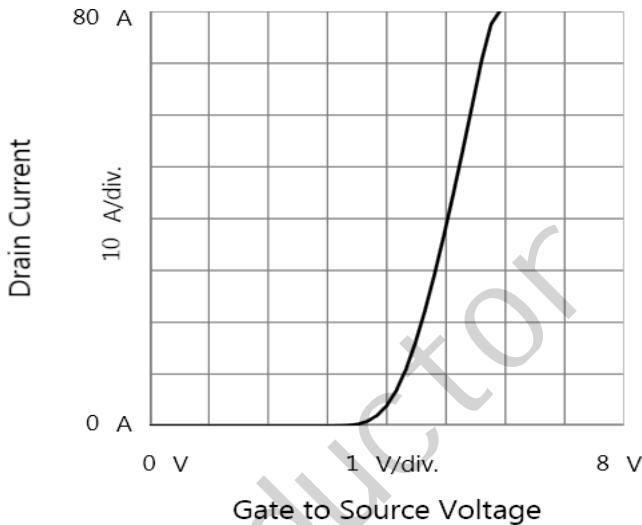


Figure 3. Drain to Source Resistance vs. Drain Current

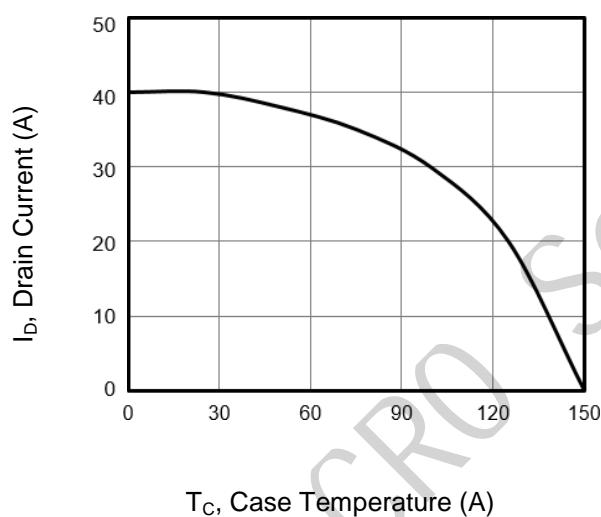


Figure 4.  $\text{BV}_{\text{DSS}}$  Variation vs. Temperature

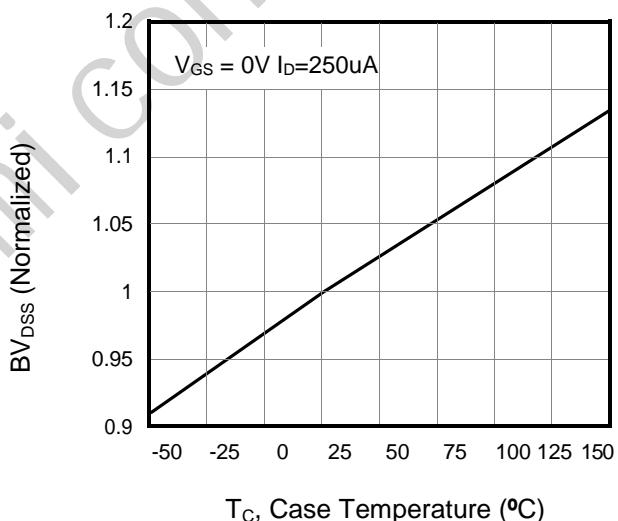


Figure 5. Drain to Source Voltage vs. Gate to Source Voltage

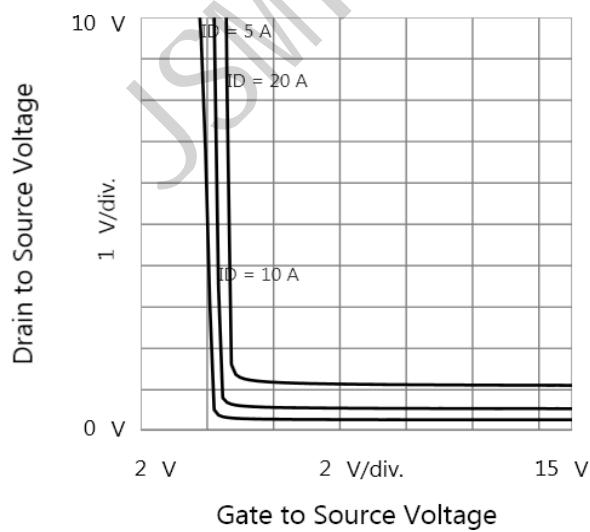
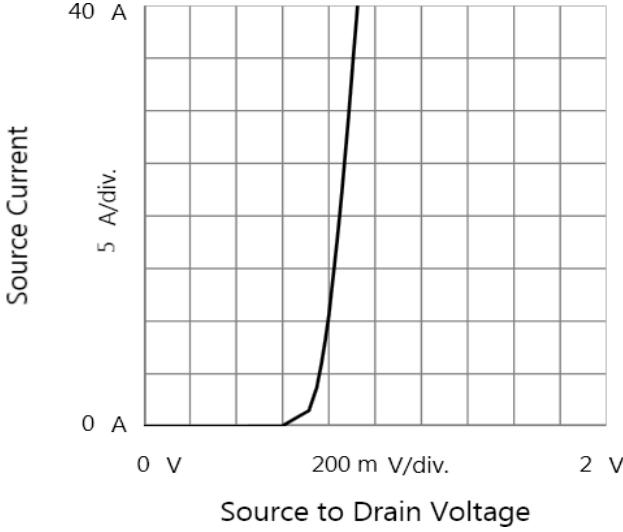
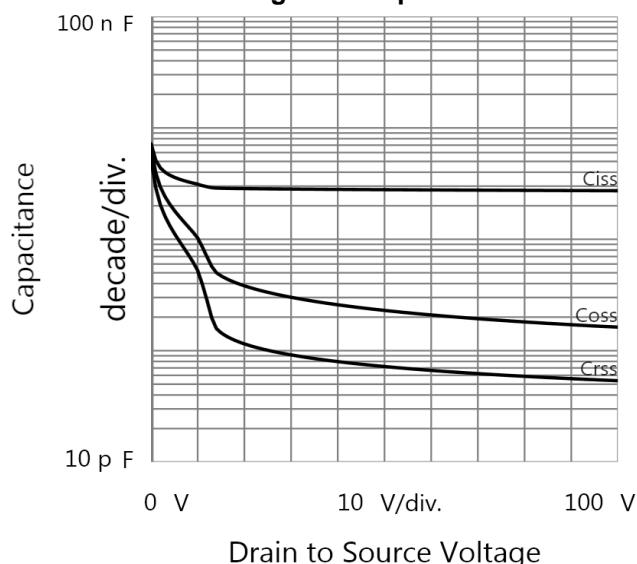


Figure 6. Body Diode Forward Characteristics

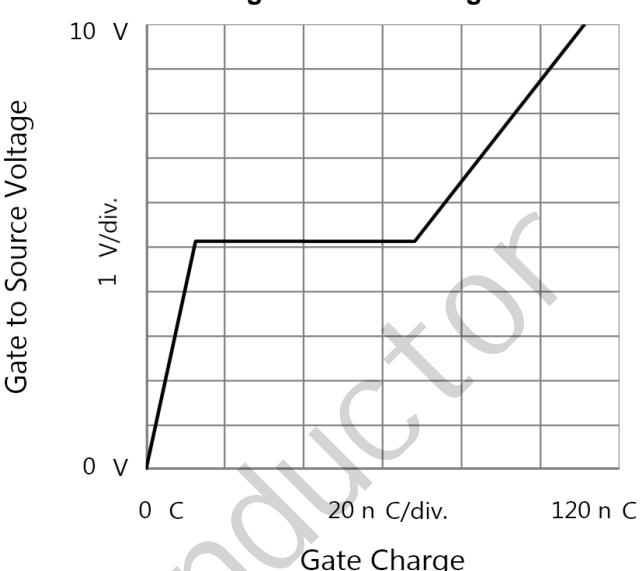


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

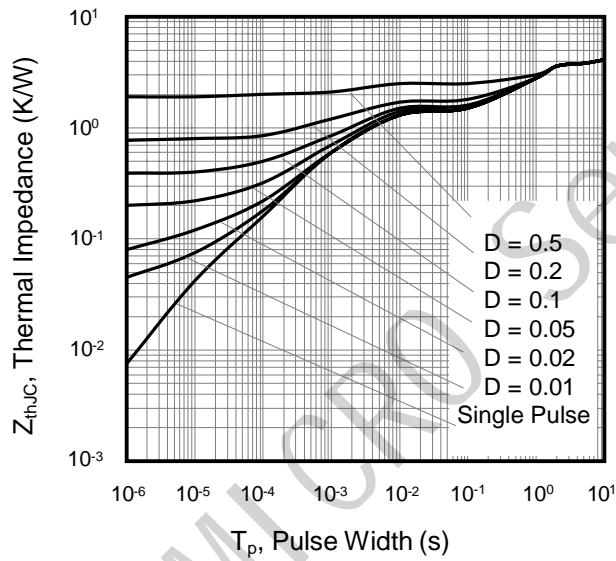
**Figure 7. Capacitance**



**Figure 8. Gate Charge**



**Figure 9. Transient Thermal Impedance  
TO-220**



**Figure 10. Transient Thermal Impedance  
TO-220**

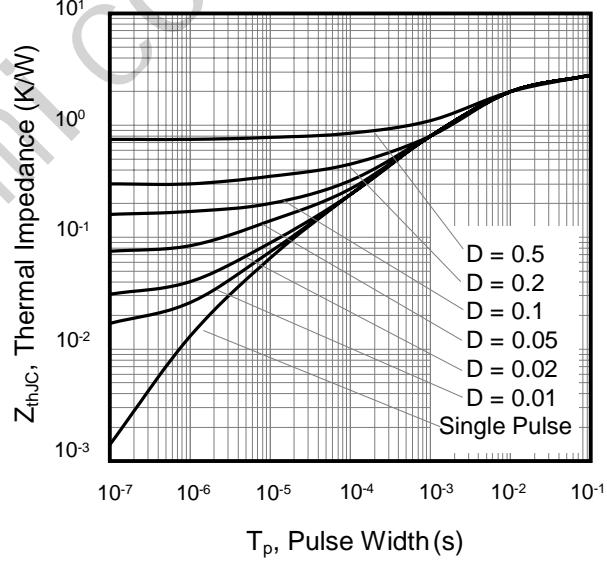


Figure A: Gate Charge Test Circuit and Waveform

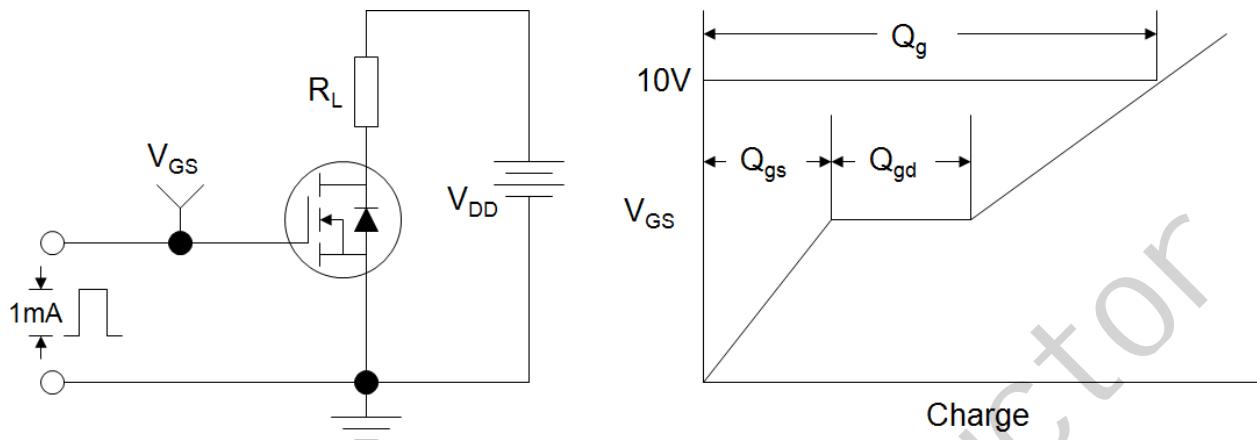


Figure B: Resistive Switching Test Circuit and Waveform

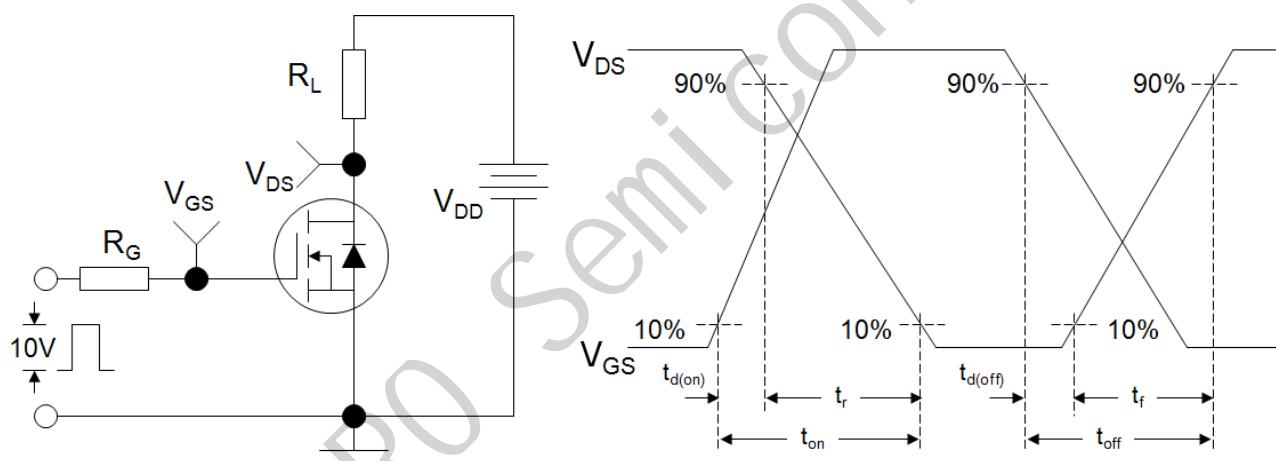
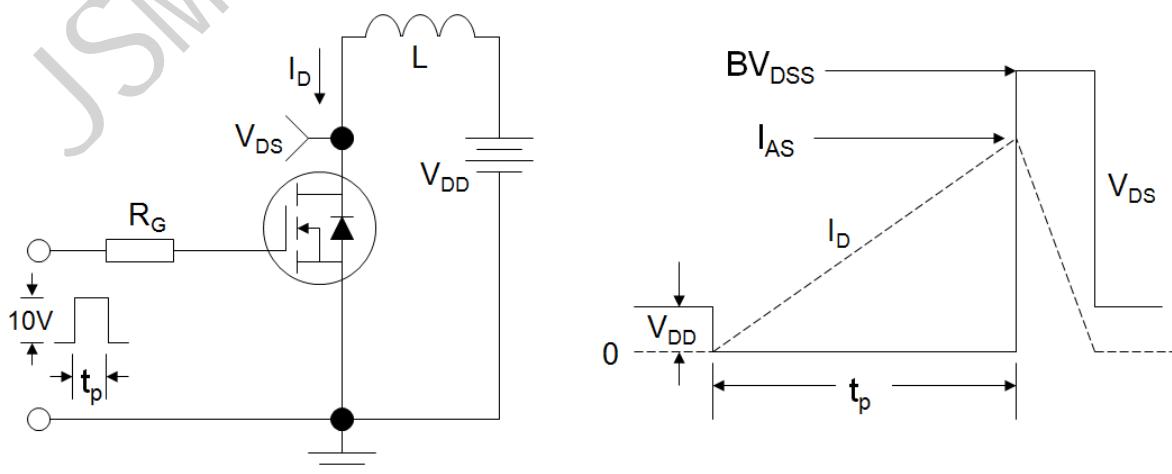
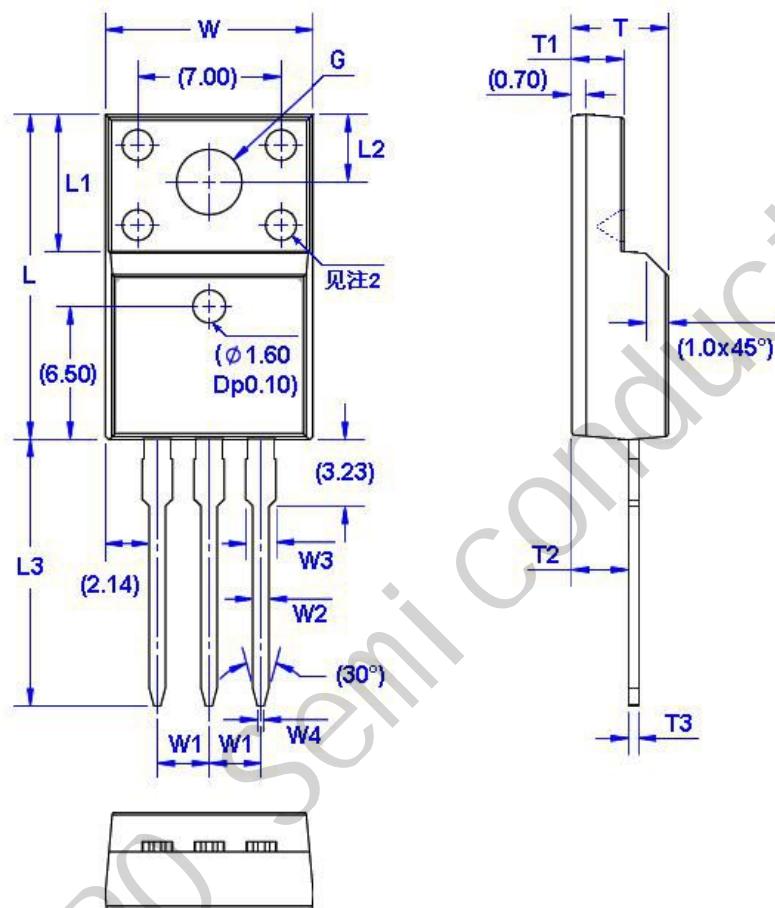


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



## Package Outline: TO-220



Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.96	10.36	W4	0.25	0.45	L3	12.78	13.18	T3	0.45	0.60
W1	2.54 (TYP)		L	15.67	16.07	T	4.50	4.90	G(Φ)	3.08	3.28
W2	0.70	0.90	L1	6.48	6.88	T1	2.34	2.74			
W3	1.24	1.47	L2	3.20	3.40	T2	2.56	2.96			

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